

Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1. (Currently Amended) A ceramic capacitor, comprising: a first conductive pattern; a second conductive pattern and a dielectric layer, the first conductive pattern and the second conductive pattern being made of a conductor and provided so as to oppose each other and sandwich the dielectric layer therebetween, the first conductive pattern and the second conductive pattern being different in area from each other, where the second conductive pattern is smaller than the first conductive pattern, and a portion where the first conductive pattern and the second conductive pattern overlap each other forming a capacitance portion,
wherein a first extended portion and a second extended portion made of the conductor are formed at both edges of the second conductive pattern so as to extend in mutually opposite directions, and
the first conductive pattern has an aperture.
2. (Original) The ceramic capacitor according to claim 1, wherein an outer edge of the second conductive pattern is formed so as not to extend beyond an outer edge of the first conductive pattern.
3. (Original) The ceramic capacitor according to claim 1, wherein the first extended portion and the second extended portion of the second conductive pattern extend outwardly beyond an outer edge of the first conductive pattern.
4. (Original) The ceramic capacitor according to claim 1, wherein a width of each of the first extended portion and the second extended portion of the second conductive pattern is narrower than a width of the first conductive pattern.
5. (Currently Amended) The ceramic capacitor according to claim 1, wherein ~~neither of the first conductive pattern nor the second conductive pattern~~ does not have ~~has~~ an aperture.

6. (Cancelled)

7. (Currently Amended) The ceramic capacitor according to claim 6-1, wherein the second conductive pattern is formed with a strip-shaped pattern whose central portion lies across the aperture of the first conductive pattern and both end portions overlap the first conductive pattern.

8. (Original) The ceramic capacitor according to claim 7, wherein the second conductive pattern formed in the strip shape has a swelling portion at an overlapping portion with the aperture of the first conductive pattern, the swelling portion having an increased width compared with other portions and for the connection with a via electrode.

9. (Original) The ceramic capacitor according to claim 7, wherein a third conductive pattern further is formed integrally at least at one end portion of the second conductive pattern, the third conductive pattern overlapping the first conductive pattern so as to form capacitance.⁴

10. (Original) The ceramic capacitor according to claim 1, wherein the first extended portion and the second extended portion of the second conductive pattern have a same width.

11. (Original) The ceramic capacitor according to claim 1, wherein the first extended portion and the second extended portion of the second conductive pattern are present along a same line.

12. (Original) The ceramic capacitor according to claim 1, wherein the first extended portion and the second extended portion of the second conductive pattern are present in parallel lines.

13-14. (Cancelled)

15. (Original) A method for producing a ceramic capacitor, comprising the steps of:
forming a first conductive pattern serving as one electrode of the capacitor on a first green sheet;
forming a second conductive pattern serving as the other electrode of the capacitor on a second green sheet; and

laminating the first green sheet and the second green sheet, followed by sintering of the same,

wherein an aperture is formed in the first conductive pattern so as to penetrate in a same direction as a direction of the lamination, and

in projection in the lamination direction, the second conductive pattern is formed with a strip-shaped pattern whose central portion lies across the aperture and both end portions overlap the first conductive pattern.

16-18. (Cancelled)

19. (Original) A dielectric multilayer device, comprising: a plurality of dielectric layers and a plurality of conductive patterns, which are laminated alternately in a vertical direction having an interval therebetween; and a capacitor that is built in the dielectric multilayer device,

wherein the capacitor comprises: a first dielectric layer; and a first conductive pattern and a second conductive pattern made of a conductor provided so as to oppose each other and sandwich the first dielectric layer therebetween in a direction of a thickness of the first dielectric layer,

an aperture is formed in the first conductive pattern so as to penetrate in a same direction as the direction of the thickness of the first dielectric layer, and

in projection in the thickness direction, the second conductive pattern is formed with a strip-shaped pattern whose central portion lies across the aperture and both end portions overlap the first conductive pattern.

20. (Original) The dielectric multilayer device according to claim 19, wherein the first dielectric layer constituting the capacitor is formed thinner than any dielectric layers sandwiched between conductive patterns other than the first and the second conductive patterns.